APPLICATION DATA SHEET

Inventor Information

Inventor One Given Name : Tim Family Name : Murphy

Postal Address Line One : 2817 McKinney Street

City : Boise
State or Province : Idaho
County : Ada
Postal or Zip Code : 83704
City of Residence : Boise
State or Prov. Of Residence : Idaho
Country of Residence : USA
Citizenship Country : USA

Inventor Two Given Name : Lee Family Name : Gotcher

Postal Address Line One : 3914 North Collister Drive

Citv Boise State or Province : Idaho County : Ada Postal or Zip Code 83703 City of Residence Boise State or Prov. Of Residence : Idaho Country of Residence : USA Citizenship Country USA

Correspondence Information

Name Line One : Steven H. Arterberry, Esq.
Address Line One : DORSEY & WHITNEY LLP
Address Line Two : 1420 Fifth Avenue, Suite 3400

City : Seattle
State or Province : Washington
Postal or Zip Code : 98101

Telephone : 206-903-8800 Facsimile : 206-903-8820

E-Mail : patentseattle@dorsey.com

Application Information

Title METHOD AND SYSTEM FOR ELECTRICALLY

COUPLING A CHIP TO CHIP PACKAGE

Total Drawing Sheets 3 Formal Drawings YES Application Type Utility Attorney Docket Number

501039.03

Yes (Large Entity) Assigned

Representative Information

Representative Customer No. 27,076

Continuity Information

This application is a : divisional of Application One : 09/978,983

Filing Date : October 15, 2001

h:\ip\documents\clients\micron technology\1000\501039.03\501039.03 app data sheet.doc